



Features

- 4-Pin SMD package
- Fast warm-up
- Frequency Range, 10 MHz to 40 MHz
- Standard freq: 10, 12.8, 20, 24.576, 25, 30.72 MHz,
- High Relability (based on fully intergrated Design)
- Low Power

Applications

- Base stations (5G & 4G)
- Test equipment
- Small Cell
- Military communication equipment
- Stratum 3
- SyncE; 1588

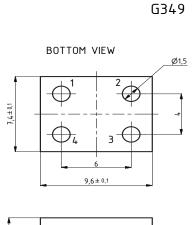
Performance Specifications

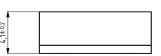
Frequency Stabilities ¹ 10 to 40 MHz						
Parameter	Min	Typical	Max	Units	Condition	
vs. operating temperature range (referenced to +25°C)	-20 -10 -20		+20 +10 +20	ppb ppb ppb	-40 to +85°C -40 to +85°C -40 to +95°C	Options ⁵
slope	-2		+2	ppb/°C	@ Temp stab. +-10ppb	
Initial tolerance vs. supply voltage change vs. load change vs. aging / day vs. aging / year vs. aging / 10 years	-0.5 -10 -10 -5 500 -3	±3 ±2 ±2	+0.5 +10 +10 +5 +500	ppm ppb ppb ppb ppb ppm	at time of shipment, nominal EFC $V_s\pm5\%$ static Load $\pm5\%$ static after 30 days of operation after 30 days of operation after 30 days of operation	
Holdover drift			5	ppb	over 24 hours, constant temperature (<±1° after 30 days continous opperation	°C);
Start up time			200	msec		
Warm-up time			3	minutes	to ±50ppb of final frequency (1 hour readi @ +25°C	ing)
Loop bandwith for wander generation compliance	3			mHz	MTIE compliant with GR-1244 Fig 5-5 TDEV compliant with GR- 1244 Fig 5-4; measurement setup: oscillator stabilized hours at Constant Temperature (±1°C, sti air), data collected over 100,000 seconds a second intervals (-3dB cutoff, 1st order his pass loop filter)	24 ill at 1

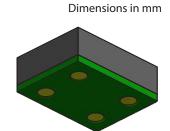
Performance Specifications

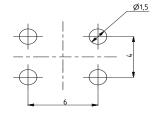
Supply Voltage (Vs)						
Parameter	Min	Typical	Max	Units	Condition	
Supply voltage (standard)	3.135	3.3	3.465	VDC		
Power consumption		1.3	1.5	Watts	during warm-up	
Power consumption		0.4	0.5	Watts	steady state @ +25℃	
			RF Outpu	t		
Signal [standard]	Signal [standard] LVHCMOS					
Load		15		pF		
Signal Level (Vol)			0.4	VDC	with Vs=3.3V and 15pF Lo	ad
Signal Level (Voh)	2.97	3.3		VDC	with Vs=3.3V and 15pF Load	
Duty Cycle	45		55	%	@ (Voh-Vol)/2	
Ron		26.5		Ω		
Roff		22		Ω		
Frequency Tuning (EFC)						
Tuning Range Fixed OCXO; No adjust						
Additional Parameters						
Phase Noise ³		-99 -125 -145 -155 -160	-90 -120 -140 150 -155	dBc/Hz dBc/Hz dBc/Hz dBc/Hz dBc/Hz	10 Hz 100 Hz 1 kHz 10 kHz 100kHz	@ 20MHz
Weight			1.0	g		
Processing & Packing	Handling & Processing Note					
Absolute Maximum Ratings						
Supply voltage (Vs)	3.8 V with Vs=3.3 VDC		with Vs=3.3 VDC			
Output Load			50	pF		
Operable Temperature Range	-40		+95	°C		
Storage Temperature Range	-40		+125	°C		

Outline Drawing / Enclosure







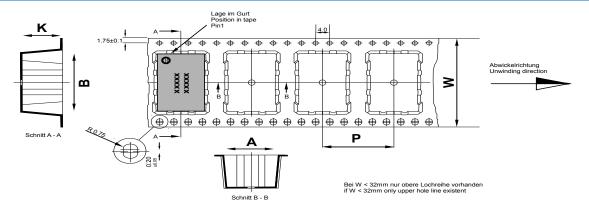


OX-601		
Height "H"	cover material	
4.1	plastic	

Pin Connections			
1	I.C (Do not connect) / EFC (option)		
2	Ground (Case)		
3	RF Output		
4	Supply Voltage Input		

Recommended Pad Layout

Standard Shipping Method (OX-601)



Maßangaben in mm:

Dimension in mm:

A, B und K Maße von Bauelement abhängig

A, B und K are dependent uppon component dimensions

All dimensions in millimeters unless otherwise stated

Fertigungstoleranzen entsprechen der DIN IEC 286-3 production tolerance complying DIN IEC 286-3

Enclosure Type	Tape Width W (mm)	Quantity per meter	Quantity per reel	Dimension P
OX-601 (4.1 mm)	24	83.3	850	12

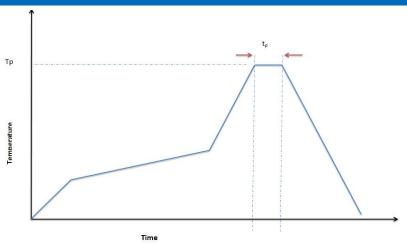
Reflow Profile

TP: max 250° C (@ solder joint, customer board level) Tp: max: 10...40 sec

Additional Information:

This SMD oscillator has been designed for pick and place reflow soldering

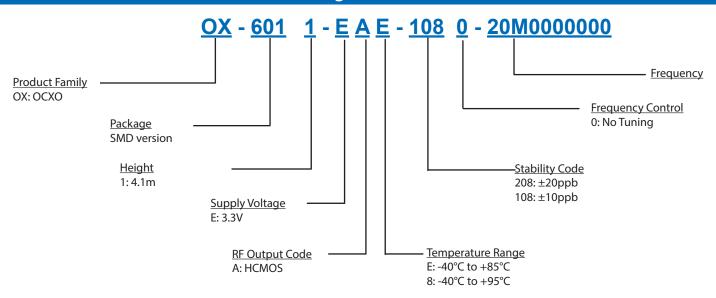
SMD oscillators must be on the top side of the PCB during the reflow process. $\label{eq:pcb} % \begin{center} \begin{centen$



Additional Environmental Conditions

Parameter	Description	
Temperature Cycling	JESD22-A104-D Cond.G - 500cycles -40/+125C;cycle time 30min	
Vibration, Sine	MIL-STD-883 Meth 2007 Cond A - 20g 20-2000Hz 4x in each 3 axis 4min sweep time	
Mechanical Shock	MIL-STD-202 Meth 213B Cond. F - 1500g 0,5ms 6 shocks in each direction	
Solderability	J-STD-002C Cond. A, Trough hole device; Cond.B, SMD (correspond to MIL-STD-883 Meth 2003) - 255C (diving T 0,5sec.) Dip&Look with 8h damp pre-treatment: solder wetting >95%	
Solvent resistance	MIL-STD-883 Meth 2003) - 255C (diving Time 5 0,5sec.) Dip&Look with	
ESD	8h damp pre-treatment: solder wetting >95%	
Moisture Sensit.	JESD22-A113-B - only if > MSL 1	
RoHS compliance	100% RoHS 6 compliant	
Washable	non-washable device	
High temp operating life(HTOL)	MIL-STD-202 Meth108A Cond C - 1000h @ 105C power on	
Low temp operating life(LTOL)	IEC 60068-2-1 Cond. Ae - 1000h @ -40C power on	

Ordering Information



Notes:

- Contact factory for improved stabilities or additional product options. Not all options and codes are available at all frequencies.
- Unless other stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C).
- 3. Phase noise degrades with increasing output frequency.
- 4. Subject to technical modification.
- 5. Contact factory for availability.



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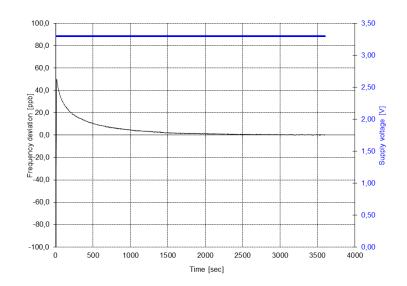
typical perforamce data

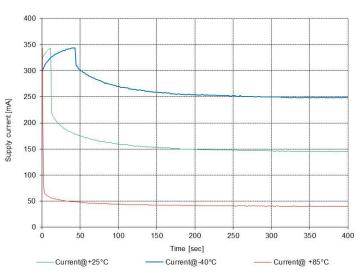
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typical current consumption during power on

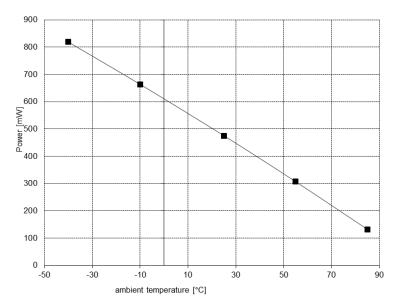
@ OX-6011-EAE-1080-20M000

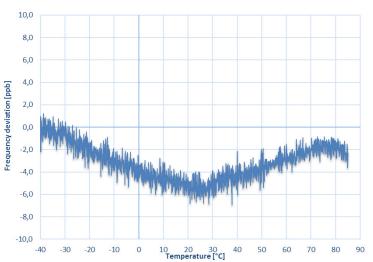
@ OX-6011-EAE-1080-20M000



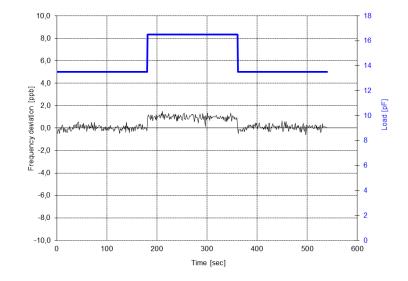


	typical power consumption vs. operating temperauture	typical frequency vs. temperature stability
Ī	@ OX-6011-EAE-1080-20M000	@ OX-6011-EAE-1080-20M000

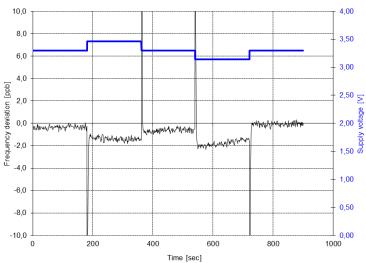




typical perforamce data typical frequency vs. load change typical frequeny vs. supply voltage



@ OX-6011-EAE-1080-20M000



@ OX-6011-EAE-1080-20M000

typical frequency. vs cycled airflow without additional cover	typical frequency. vs cycled airflow with additional cover		
@ OX-6011-EAE-1080-20M000	@ OX-6011-EAE-1080-20M000		

